# Product End-of-Life Disassembly Instructions

## Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCA</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries  Battery package &amp; lithium coin</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LED</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>PC4125/ PC4126/ PC9245/ PT4101</td>
<td>4</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>N/A</td>
</tr>
</tbody>
</table>
2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #2 Philips screw drivers (For disassemble 1 pcs screw on L-Case for ODD)</td>
<td>#1 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Description #2 Philips screw drivers (For disassemble 2 pcs screws on L-Case for HDD)</td>
<td>#1 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Description #3 Philips screw drivers (For disassemble 2 pcs screws on L-Case for Keyboard)</td>
<td>#1 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Description #4 Philips screw drivers (For disassemble 20 pcs screws on L-Case &amp; U-Case for U-Case)</td>
<td>#1 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Description # Philips screw drivers (For disassemble 1 pcs screw on U-Case for Power Board)</td>
<td>#1 2.55-3.00kgf.cm</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble Battery Package
2. Disassemble Door
3. Remove 1 screw and disassemble ODD
4. Remove 2 screws and disassemble HDD
5. Remove 2 screws and disassemble keyboard
6. Remove 20 screws and disassemble U-Case sub-assemble
7. Remove 1 screw and disassemble Power Board
8. Remove 2 screws and disassemble main speakers
9. Remove 2 screws and disassemble touch pad bracket
10. Remove 1 screws and disassemble fingerprinter module
11. Remove 2 screws and disassemble pick button board
12. Remove 1 screws and disassemble USB board
13. Remove 4 screws and disassemble Hinge-up sub-assemble
14. Remove 2 screws and disassemble sub-woofer
15. Remove 3 screws and disassemble mother board
16. Remove 2 screws and disassemble ODD cable

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Get Component
1. Battery Package
2. ODD Module
3. HDD Module
   ○ Get Screw

Get Component
4. Keyboard
   ○ Get Screw
Get Component
5. U-Case Sub-Assemble
○ Get Screw

Get Component
6. Power Board
7. Main Speakers
8. Touch Pad Bracket
9. Finger Printer module
10. Pick Button Board
○ Get Screw
Get Component
11. USB Board
12. Hinge-Up

Get Component
13. Sub Woofer

PSG instructions for this template are available at EL-MF877-01
Get Component
14. Mother Board
15. ODD cable
○ Get Screw